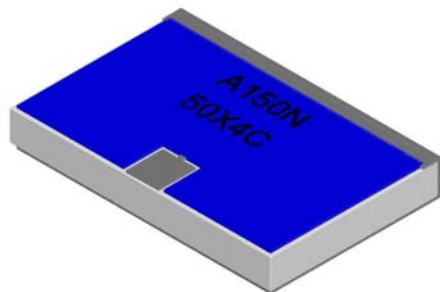


### Chip Termination 150 Watts, 50Ω



#### Description

The A150N50X4C is high performance Aluminum Nitride (AlN) chip termination intended as a cost competitive alternative to Beryllium Oxide (BeO). The termination dissipates 150W and has a return loss of 25dB to 3GHz. It is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating circulators, and for use in power combiners. The termination is also RoHS compliant!

#### General Specifications

##### Features:

- RoHS Compliant
- 150 Watts
- DC – 3.0 GHz
- AlN Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

<b>Resistive Element</b>	Thick film
<b>Substrate</b>	AlN Ceramic
<b>Terminal Finish</b>	Matte Tin over Nickel Barrier
<b>Operating Temperature</b>	-55 to +150°C

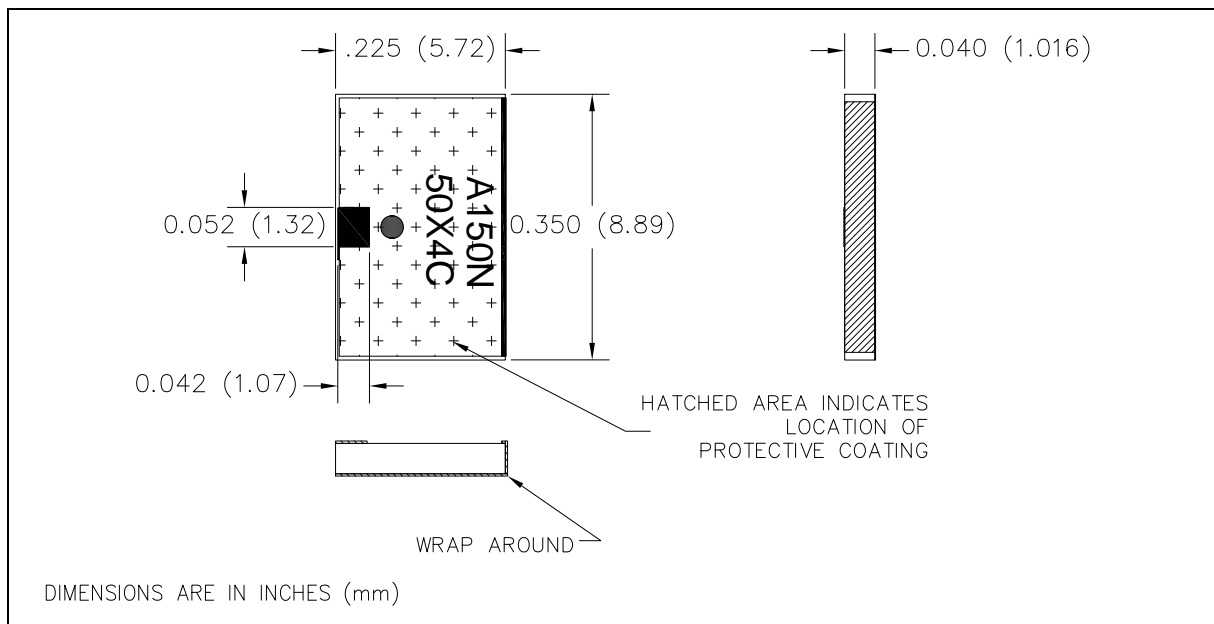
Tolerance is  $\pm 0.010$ ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

#### Electrical Specifications

<b>Resistance Value:</b>	50 Ohms, $\pm 2\%$
<b>Power:</b>	150 Watts
<b>Frequency Range:</b>	DC – 3.0 GHz
<b>V.S.W.R.</b>	1.10:1

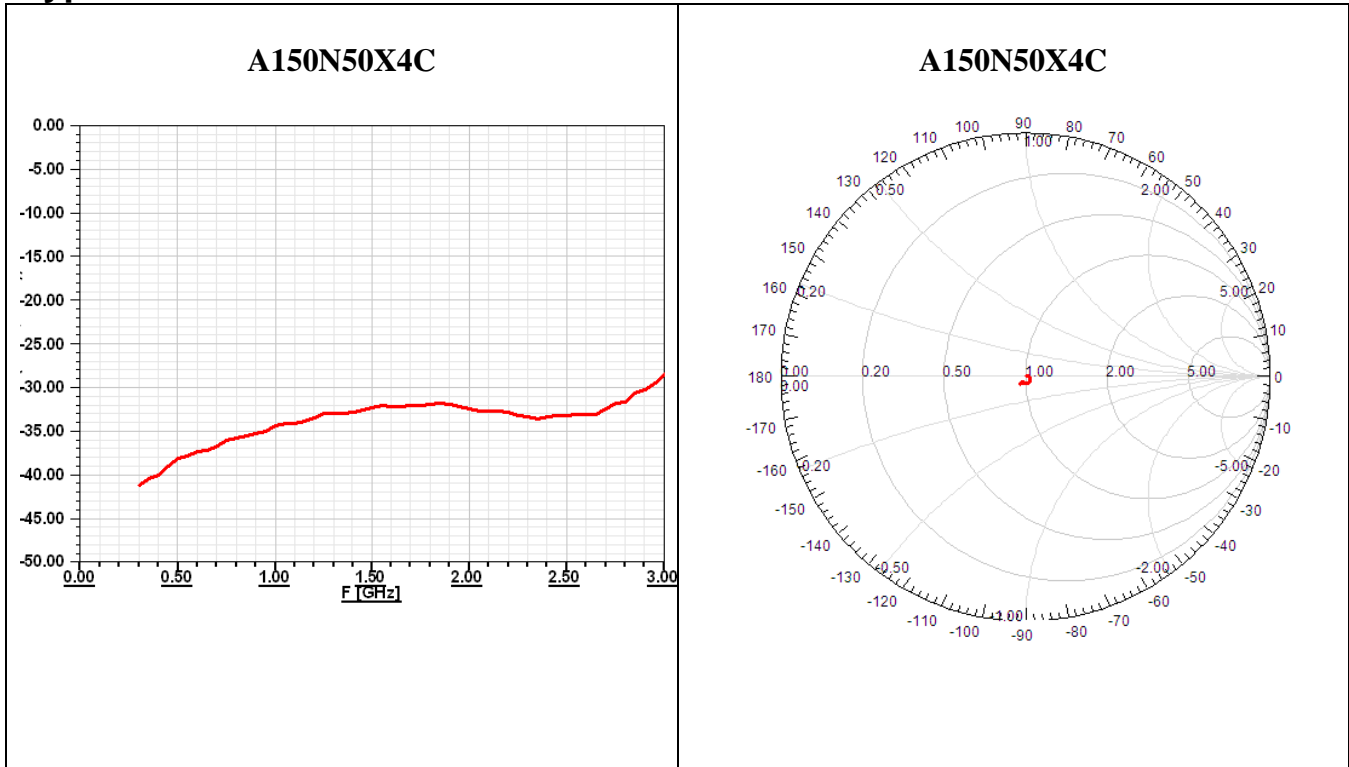
Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change.**

#### Outline Drawing

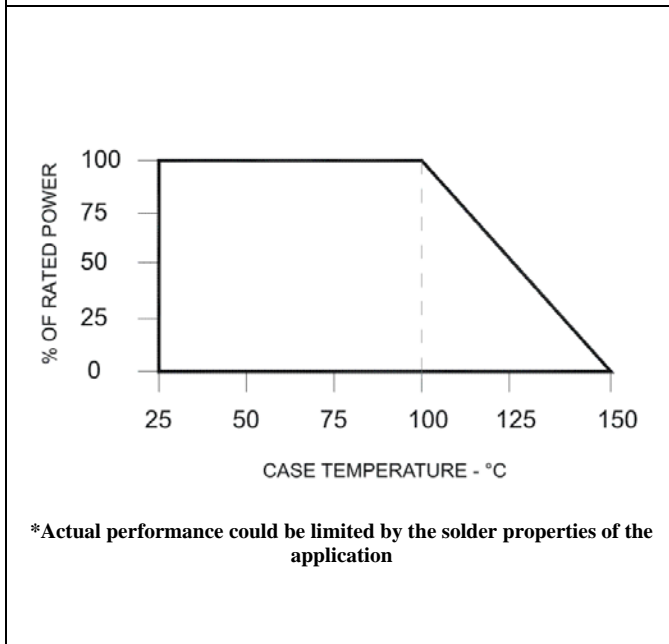


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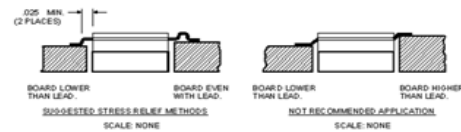
## Typical Performance:



## Power Derating:



## Suggested Mounting procedures:



### SUGGESTED MOUNTING PROCEDURE

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. POSITION DEVICE ON MOUNTING SURFACE AND SOLDER IN PLACE USING AN APPROPRIATE SOLDER.
3. SOLDER LEADS IN PLACE USING AN APPROPRIATE SOLDER TYPE WITH A CONTROLLED TEMPERATURE IRON.